LATTICE SEMICONDUCTOR

Device Material Content

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Package: **256 FOWLP**
Total Device Weight **149.49** **Milligrams**

Package Code: ASG256
Products: LFCPNX-100

Assembly: ASEK
Size (mm): 9x9mm
Lead pitch (mm): 0.5
MSL: 3
Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	50.642%	75.702	50.64%	75.702	Silicon chip	7440-21-3	100.00%	
Mold Compound	24.968%	37.324	2.257%	3.374	Proprietary Epoxy/Phenol Resins	-	9.04%	SUMIKON® EME-QXG01
			18.811%	28.119	Silica(Amorphous) A	60676-86-0	75.34%	
			3.762%	5.624	Silica(Amorphous) B	7631-86-9	15.07%	
			0.138%	0.206	Carbon Black	1333-86-4	0.55%	
Polyimide 1	0.449%	0.670	0.449%	0.670	Polyimide Resin	-	100.00%	Repassivation Polyimide LTC9320-E07
RDL 1	1.171%	1.751	1.157%	1.730	Copper (Cu)	7440-50-8	98.82%	
			0.014%	0.021	Titanium (Ti)	7440-32-6	1.18%	
RDL 2	2.663%	3.980	2.649%	3.960	Copper (Cu)	7440-50-8	99.48%	
			0.014%	0.021	Titanium (Ti)	7440-32-6	0.52%	
Polyimide 2	0.889%	1.329	0.889%	1.329	Polyimide Resin	-	100.00%	Repassivation Polyimide LTC9320-E07
Polyimide 3	0.889%	1.329	0.889%	1.329	Polyimide Resin	-	100.00%	Repassivation Polyimide LTC9320-E07
UBM	0.114%	0.171	0.014%	0.021	Titanium (Ti)	7440-32-6	12.14%	
			0.100%	0.150	Copper (Cu)	7440-50-8	87.86%	
Bump	18.216%	27.230	16.394%	24.507	Tin	7440-31-5	90.00%	SACQ
			0.729%	1.089	Silver	7440-22-4	4.00%	
			0.146%	0.218	Copper	7440-50-8	0.80%	
			0.018%	0.027	Nickel	7440-02-0	0.10%	
			0.929%	1.389	Bismuth	7440-69-9	5.10%	
					Germanium			
	100.000%	149.486	100.000%	149.486				

Notes:

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Br/Cl/Sb

Pb lead-free

RoHS

Rev. B2